

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1792AIN8#PBF

(Engineering Calculation)

FDP

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TOTAL MASS (g): 0.499483

| COMPONENT MATERIAL | VENDOR INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL Pkg. | | |
|-----------------------------|----------------------------------|--------------------------------|--------------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002685 | 1000000 | 5375.55817578 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000643 | 1000000 | 1287.33044434 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.089088 | 580000 | 178360.328125 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.064512 | 420000 | 129157.484375 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead Frame Total: | | | | 0.153600 | 1000000 | 307517.8125 |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.012410 | 1000000 | 24846.2597656 | | |
| | | External Plating Total: | | | | 0.012410 | 1000000 | 24846.2597656 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001228 | 1000000 | 2458.54101562 | | |
| | | Internal Plating Total: | | | | 0.001228 | 1000000 | 2458.54101562 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000846 | 750000 | 1691.75036621 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.002582 | 250000 | 564.583435689 | | |
| | | Die Attach Total: | | | | 0.001128 | 1000000 | 2258.3374023 |
| | | Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.078601 | 240000 | 157364.640625 |
| Bromine (Br) | 40039-03-8 | | | 0.003275 | 10000 | 6556.77636719 | | |
| Silica (SiO2) | 60676-86-0 | | | 0.215802 | 720000 | 472091.875 | | |
| Antimony Trioxide (Sb2O3) | 1309-64-4 | | | 0.009825 | 30000 | 19670.328125 | | |
| Metal Hydroxide | | | | 0.000000 | 0 | 0 | | |
| Carbon Black (C) | 1333-86-4 | | | 0.000000 | 0 | 0 | | |
| Encapsulation Total: | | | | | | 0.327503 | 1000000 | 655683.625 |
| Bond Wire Estimated | AFW/TANAKA/Kn | Gold (Au) | 7440-57-5 | 0.000286 | 1000000 | 572.59173584 | | |

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